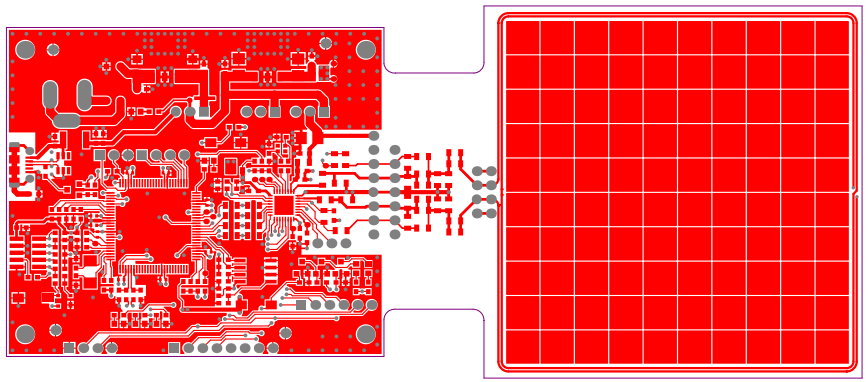
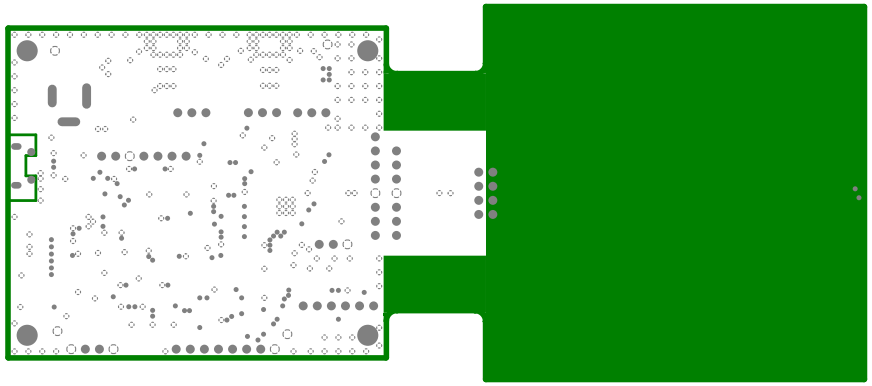


Title: *CLEV6630B*	
Date: 11.05.2017	Revision: V2.0
File: CLEV6630B_V2.0.PcbDoc	Designed by:



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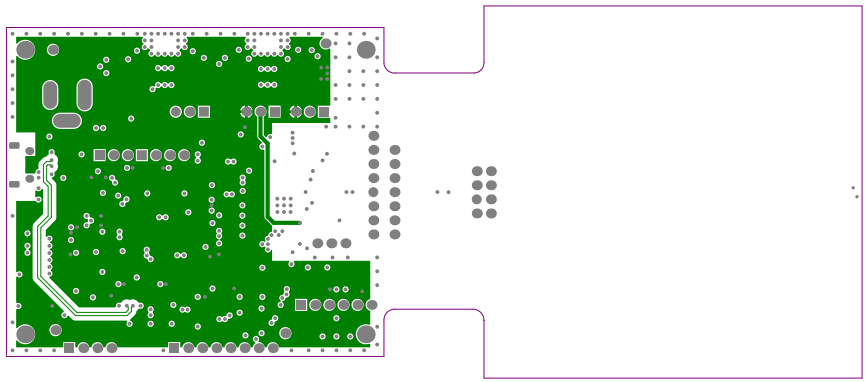
Date: 11.05.2017	Revision: V2.0
File: CLEV6630B_V2.0.PcbDoc	Designed by:



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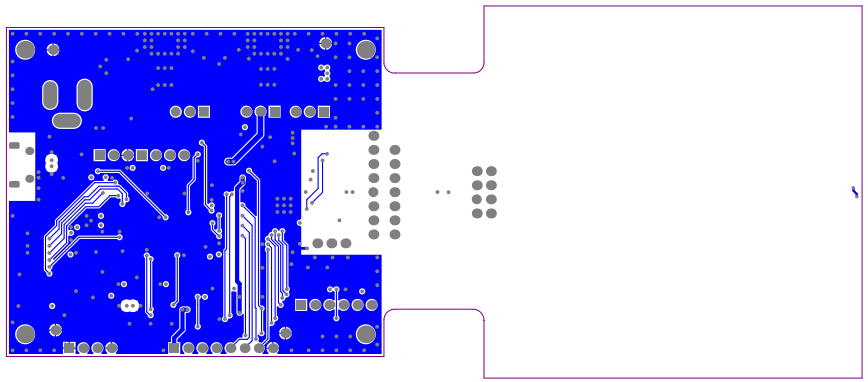
Date: 11.05.2017	Revision: V2.0
File: CLEV6630B_V2.0.PcbDoc	Designed by:



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Date: 11.05.2017	Revision: V2.0
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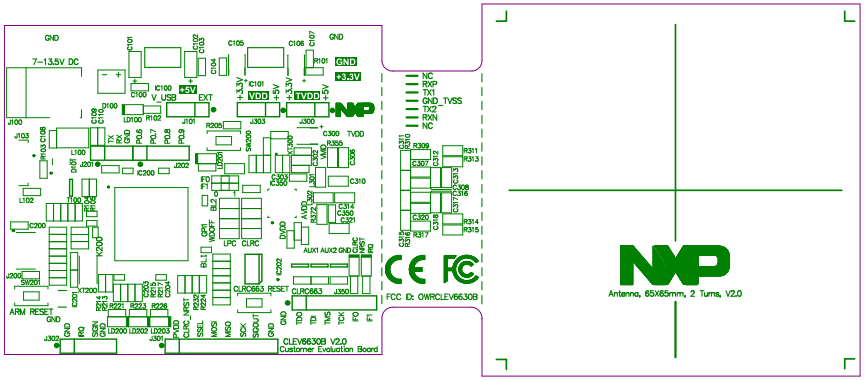

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Date: 11.05.2017	Revision: V2.0
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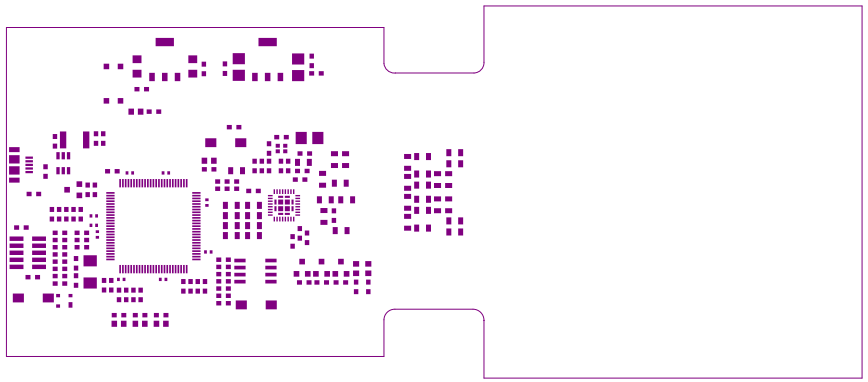

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Date: 11.05.2017	Revision: V2.0
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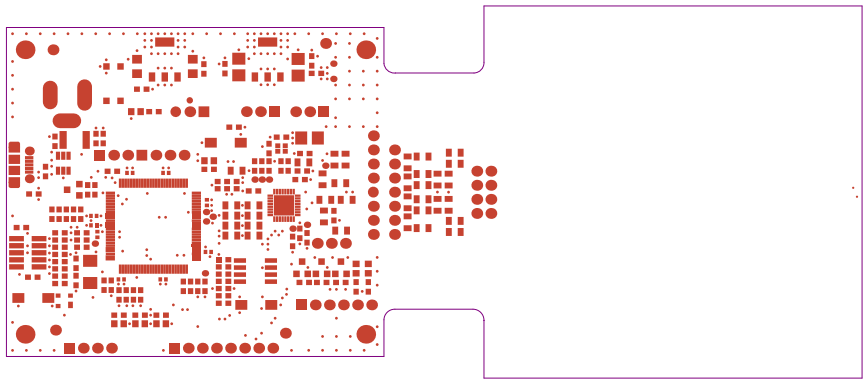

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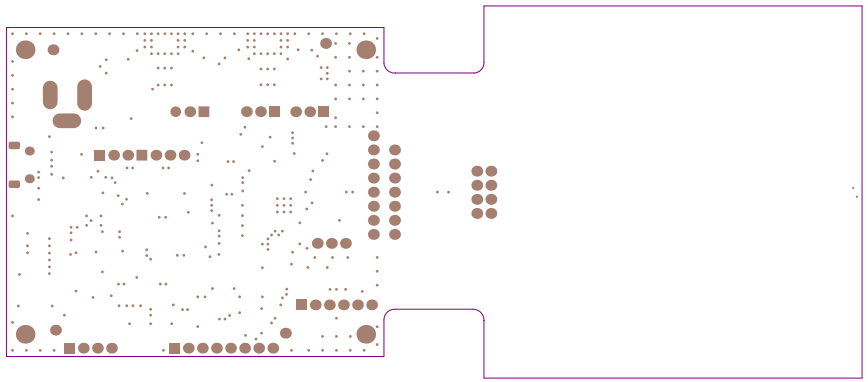
Date: 11.05.2017	Revision: V2.0
File: CLEV6630B_V2.0.PcbDoc	Designed by:



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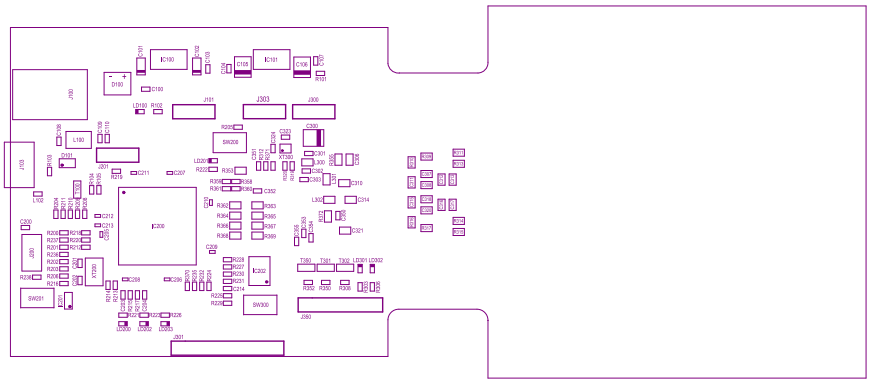
Date: 11.05.2017	Revision: V2.0
File: CLEV6630B_V2.0.PcbDoc	Designed by:



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Date: 11.05.2017	Revision: V2.0
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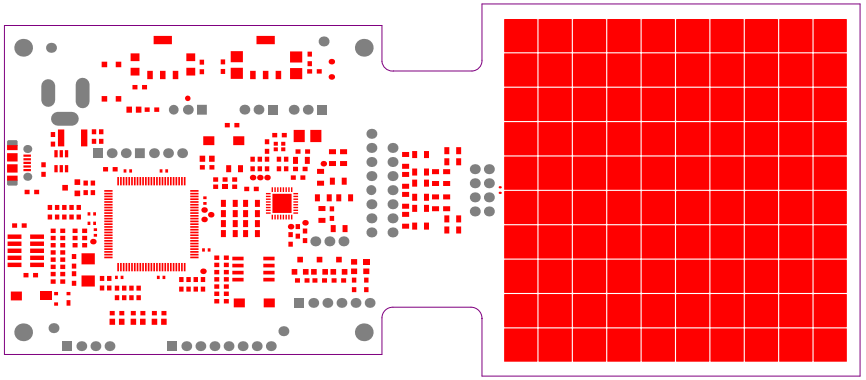
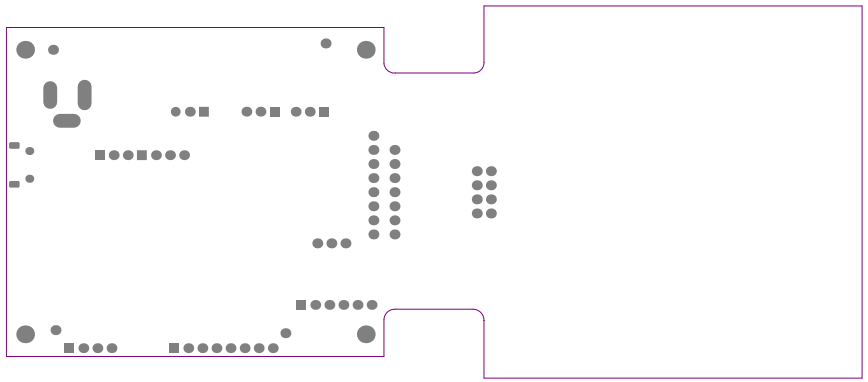


Title: *CLEV6630B*	
Date: 11.05.2017	Revision: V2.0
File: CLEV6630B_V2.0.PcbDoc	Designed by:



Title: *CLEV6630B*	
Date: 11.05.2017	Revision: V2.0
File: CLEV6630B_V2.0.PcbDoc	Designed by:

Master Drawings:

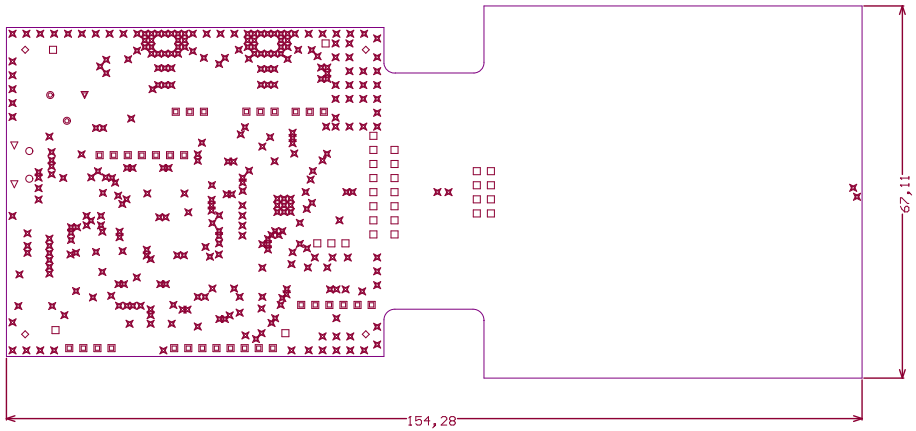
- material: FR4, Tg: 150
- thickness: 1,6mm (min 1,44, max 1,7mm)
- layer stackup: - Top Cu: 35um
  - prepreg 0,14mm
  - Internal Plane1 Cu: 35um
  - core 1,0mm
  - MidLayer1 Cu: 35um
  - prepreg 0,14mm
  - Bottom Cu: 35um
- min. hole metalization: 20um
- surface finishing: ENIG

- solder mask: - in accordance with IPC-SM-840
  - Liquid Photo Imageable (LPI)
  - color: BLUE
  - unless otherwise defined (in gerber), solder mask overlap on SMT pads is not allowed

- silk screen: Yes, White
- impedance control: Yes, see table below
- board must meet the acceptable level of IPC-A-600, Class 2, current revision.
- bow and twist: - max. 0.75% SMT boards
  - max. 1.5% THT boards
- point of origin (0,0): bottom left corner
- board is designed on 0,050 mm grid
- primary side: Top layer

Impedance table:

	Differentail pair 90 [ohm] Width / Spacing [mm]
Layer1	0.22 / 0.3
Layer2	
Layer3	0,18 / 0,40
Layer4*	0.22 / 0.3



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
▽	1	1,000mm (39,37mil)	PTH	Slot
▽	2	0,600mm (23,62mil)	PTH	Slot
○	2	0,850mm (33,46mil)	PTH	Round
◎	2	1,000mm (39,37mil)	PTH	Slot
◇	4	3,200mm (126,00mil)	NPTH	Round
□	30	1,000mm (39,37mil)	PTH	Round
▣	34	1,016mm (40,00mil)	PTH	Round
✖	334	0,300mm (11,81mil)	PTH	Round
	409 Total			

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Title: *CLEV6630B*	
Date: 11.05.2017	Revision: V2.0
File: CLEV6630B_V2.0.PcbDoc	Designed by: